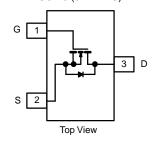
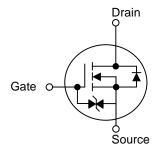


## BSS138W-VB Datasheet N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}$ (Ω) $I_{D}$ (m			
60	2 at V <sub>GS</sub> = 10 V	300		







#### FEATURES

- Halogen-free According to IEC 61249-2-21
  Definition
- Low On-Resistance: 2  $\Omega$
- Low Threshold: 2 V (typ.)
- Low Input Capacitance: 25 pF
- Fast Switching Speed: 25 ns
- Low Input and Output Leakage
- Trench Power MOSFET
- Compliant to RoHS Directive 2002/95/EC

#### BENEFITS

- Low Offset Voltage
- Low-Voltage Operation
- · Easily Driven Without Buffer
- High-Speed Circuits
- Low Error Voltage

#### **APPLICATIONS**

- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- Battery Operated Systems
- Solid-State Relays

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25 \text{ °C}$ , unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage		V <sub>DS</sub>	60			
Gate-Source Voltage	V <sub>GS</sub>	± 20	V			
Continuous Drain Current (T. 450 °C)b	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	300	mA		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>b</sup>	T <sub>A</sub> = 100 °C		190			
Pulsed Drain Current <sup>a</sup>	I <sub>DM</sub> 800					
	T <sub>A</sub> = 25 °C	- P <sub>D</sub>	0.35	14/		
Power Dissipation <sup>b</sup>	T <sub>A</sub> = 100 °C		0.14	W		
Maximum Junction-to-Ambient <sup>b</sup>	R <sub>thJA</sub>	350	°C/W			
Operating Junction and Storage Temperature Range		T <sub>J,</sub> T <sub>stg</sub>	- 55 to 150	°C		

Notes:

a. Pulse width limited by maximum junction temperature.

b. Surface Mounted on FR4 board.

\* Pb containing terminations are not RoHS compliant, exemptions may apply.



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			Limits				
Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static			•		•		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 10 \mu A$	60			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1		2.5		
		$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 10		
		$V_{DS} = 0 V, V_{GS} = \pm 15 V$			1	μA	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 10 V$			± 150	nA	
		$V_{DS} = 0 V, V_{GS} = \pm 10 V, T_{J} = 85 °C$			± 1000		
		$V_{DS} = 0 V, V_{GS} = \pm 5 V$			± 100		
Zero Gate Voltage Drain Current		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μA	
	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 125 \text{ °C}$			500		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 7.5 V	800			<u> </u>	
		$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V}$	500			mA	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 500 mA	2			Ω	
Drain-Source On-Resistance <sup>a</sup>		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 200 mA	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 200 mA				
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 200 mA	100			mS	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 200 mA, V <sub>GS</sub> = 0 V			1.3	V	
Dynamic <sup>a</sup>			I	1	<u>1</u>		
Total Gate Charge	Qg	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}$ $I_D \cong 250 \text{ mA}$		0.4	0.6	nC	
Input Capacitance	C <sub>iss</sub>			30		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 25 V, V_{GS} = 0 V$		6			
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1 MHz		2.5			
Switching <sup>a, b, c</sup>							
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 30 V, R <sub>1</sub> = 150 Ω			25		
Turn-Off Time	t <sub>d(off)</sub>	$I_D \cong 200 \text{ mA}, V_{GEN} = 10 \text{ V}, R_G = 10 \Omega$			35	ns	

Notes:

a. For DESIGN AID ONLY, not subject to production testing.

b. Pulse test: PW  $\leq$  300  $\mu s$  duty cycle  $\leq$  2 %.

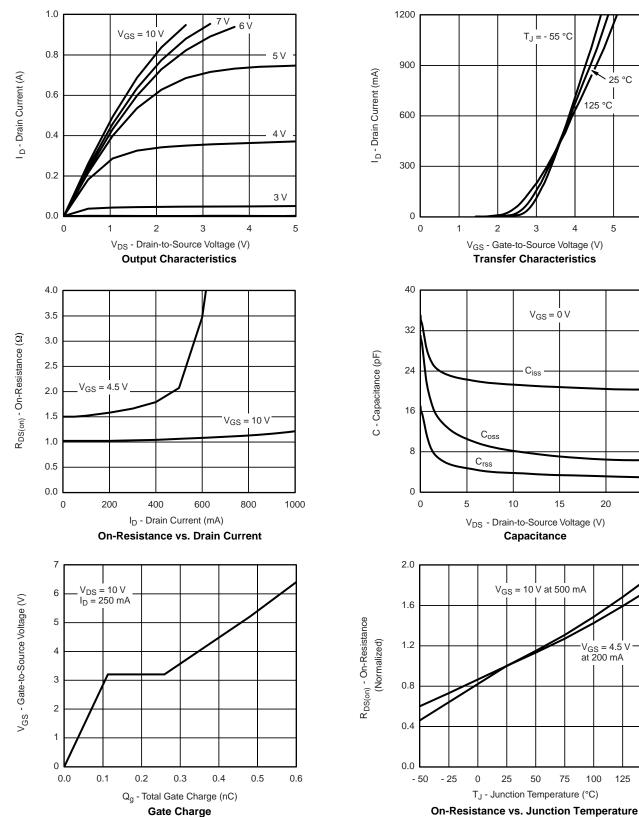
c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

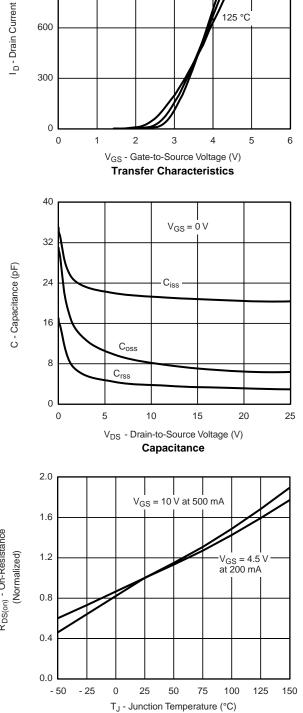


25 °C

T<sub>J</sub> = - 55 °C

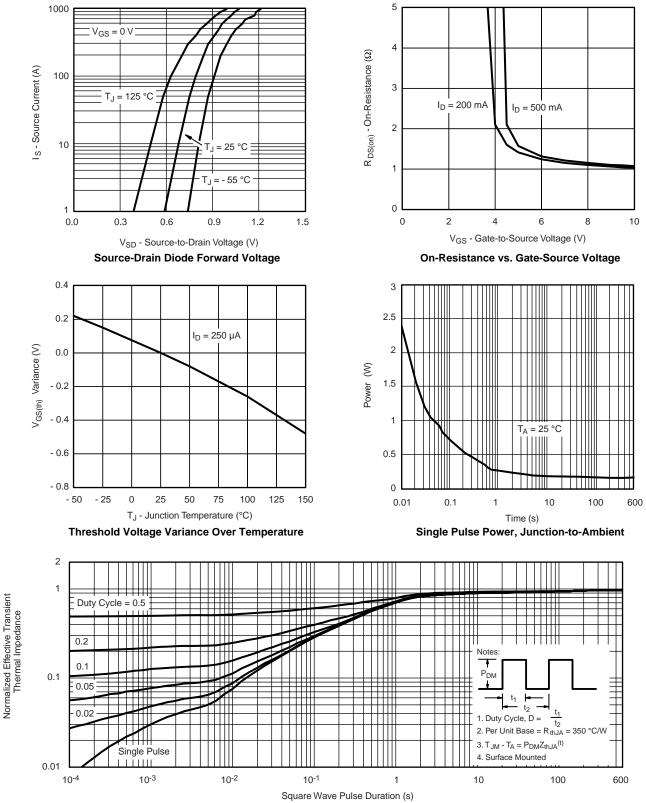


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



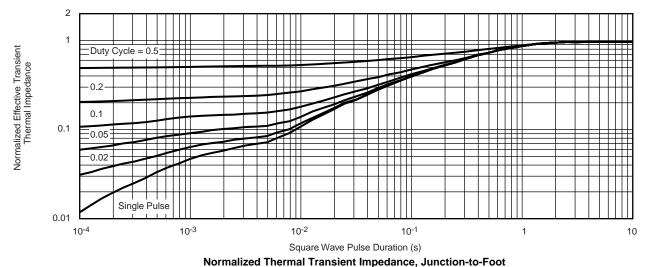


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient





#### **THERMAL RATINGS** ( $T_A$ = 25 °C, unless otherwise noted)

#### Note

• The characteristics shown in the two graphs

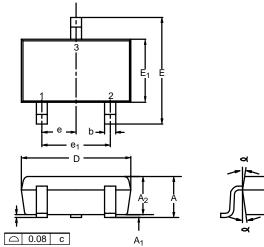
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

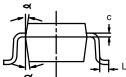
- Normalized Transient Thermal Impedance Junction-to-Foot (25 C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



### SC-70: 3-LEADS

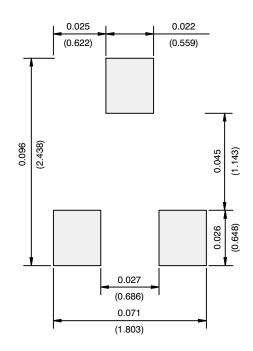




	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.90	-	1.10	0.035	-	0.043	
<b>A</b> <sub>1</sub>	-	-	0.10	-	-	0.004	
A <sub>2</sub>	0.80	-	1.00	0.031	-	0.039	
b	0.25	-	0.40	0.010	-	0.016	
С	0.10	-	0.25	0.004	-	0.010	
D	1.80	2.00	2.20	0.071	0.079	0.087	
E	1.80	2.10	2.40	0.071	0.083	0.094	
E <sub>1</sub>	1.15	1.25	1.35	0.045	0.049	0.053	
е		0.65BSC			0.026BSC		
e <sub>1</sub>	1.20	1.30	1.40	0.047	0.051	0.055	
L	0.10	0.20	0.30	0.004	0.008	0.012	
ಇ	★ 7°Nom			7°Nom			
ECN: S-03946—Rev. C, 09-Jul-01 DWG: 5549							



#### **RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead**



Recommended Minimum Pads Dimensions in Inches/(mm)



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